



xLED

xLED-OSR-7050 Pin Fin Heat Sink Φ 70mm for Osram

Features VS Benefits

- * The xLED-OSR-7050 Osram Pin Fin LED Heat Sinks are specifically designed for luminaires using the Osram LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,000 to 2,600 lumen.
- * Thermal resistance range Rth 3.13°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Osram LED engines.
- * Diameter 70.0mm - standard height 50.0mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Osram COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

OSRAM

Opto Semiconductors



Osram LED Modules directly Mounting Options

Osram SOLERIQ® S 13 COB LED modules name:

- GW KAGGxx.xx; GW KAGLxx.xx;
- GW KAGHxx.xx; GW KAGMxx.xx;
- GW KAGJxx.xx;

With the Zhaga Book 3 Holders:

- BJB holder:47.319.2021.50;
- TE LED Holder:2213254-1;

Direct mounting with machine screws M3x6.5mm, green indicator marks.

Osram SOLERIQ® S 9 COB LED modules name:

- GW KAFGxx.xx;
- GW KAFHxx.xx;
- GW KAFJxx.xx;

With the Zhaga Book 11 Holders:

- BJB holder:47.319.6060.50;
- TE LED Holder:2213678-5;

Direct mounting with machine screws M3x6.5mm, Red indicator marks.

With the LEDiL products:

- Lenins series: CN14xxx; CN13xxx; CN12xxx;
- Ronda series: FN15xxx-xx;

Osram PrevaLED Core Z5, Z6, Z7 L15 H1, AC G2 and AC PRO LED modules

- PL-CORE-Z5 -2000-xxx; PL-CORE-G7 2000-xxx L15 H1;
- PL-CORE-Z5 -3000-xxx; PL-CORE-G7 3000-xxx L15 H1;
- PL-CORE-Z6 -2000-xxx; PL-CORE AC PRO -2000-xxx;
- PL-CORE-Z6 -3000-xxx; PL-CORE AC -2000-xxx;

With the Zhaga Book 3 standard:

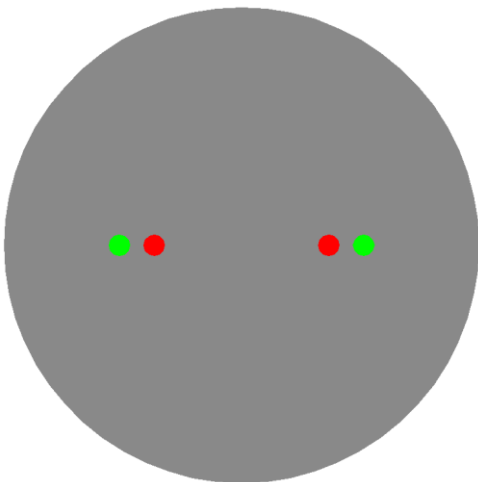
Direct mounting with machine screws M3x6.5mm, green indicator marks.

Osram PrevaLED Core Z6 Mini LED modules name:

- PL-CORE-Z6-MINI -2000-xxx;

With the Zhaga Book 11 standard:

Direct mounting with machine screws M3x6.5mm, Red indicator marks.





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Mounting Options and Drawings & Dimensions

Example:xLED-OSR-7050-B-1,2

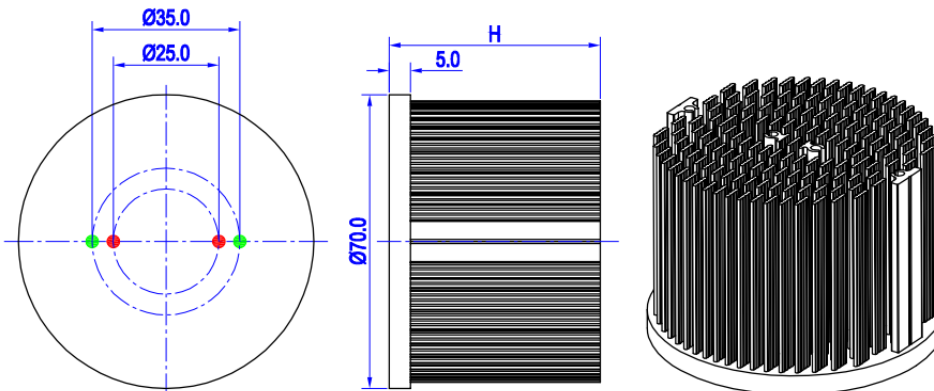
Example:xLED-OSR-70 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
 - B-Black
 - C-Clear
 - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
Ex.order code - 12
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lenina series	Ronda series			
N	/	None	None	None	None	None	None
1	SOLERIQ® S 9	BJB Holder 47.319.6060.50 TE Holder 2213678-5	CN14xxx; CN13xxx; CN12xxx;	FN15xxx-xx	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
	Z6 Mini	/					
2	Z5; Z6; Z7 L15 H1; AC G2 AC PRO;	/			M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	SOLERIQ® S 13	BJB Holder 47.319.2021.50 TE Holder 2213254-1	CN14xxx; CN13xxx; CN12xxx;	FN15xxx-xx			



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The product data table

	Model No.	xLED-OSR-7050
	Heatsink Size	Φ 70xH50mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	150.0
	Dissipated power (T_{hs-amb},50°C)	16.0 (W)
	Cooling surface area (mm²)	91577
	Thermal Resistance (R_{hs-amb})	3.13 (°C/W)

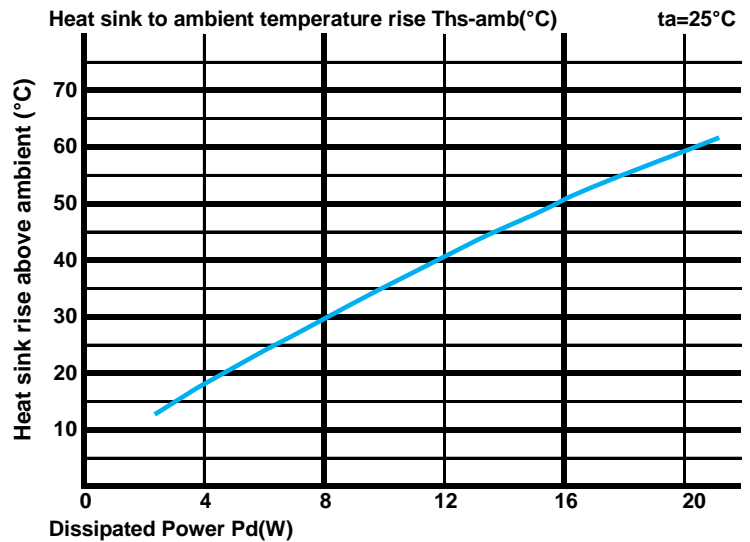
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		xLED-OSR-7050	
4.0		4.25	17.0
8.0		3.63	29.0
12.0		3.33	40.0
16.0		3.13	50.0
20.0		2.95	59.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature; T_a - Ambient temperature;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is R_{heatsink-ambient} [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package R_{interface (TIM)} and R_{heatsink-ambient} can be integrated into the thermal resistance R_{case-ambient} at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$